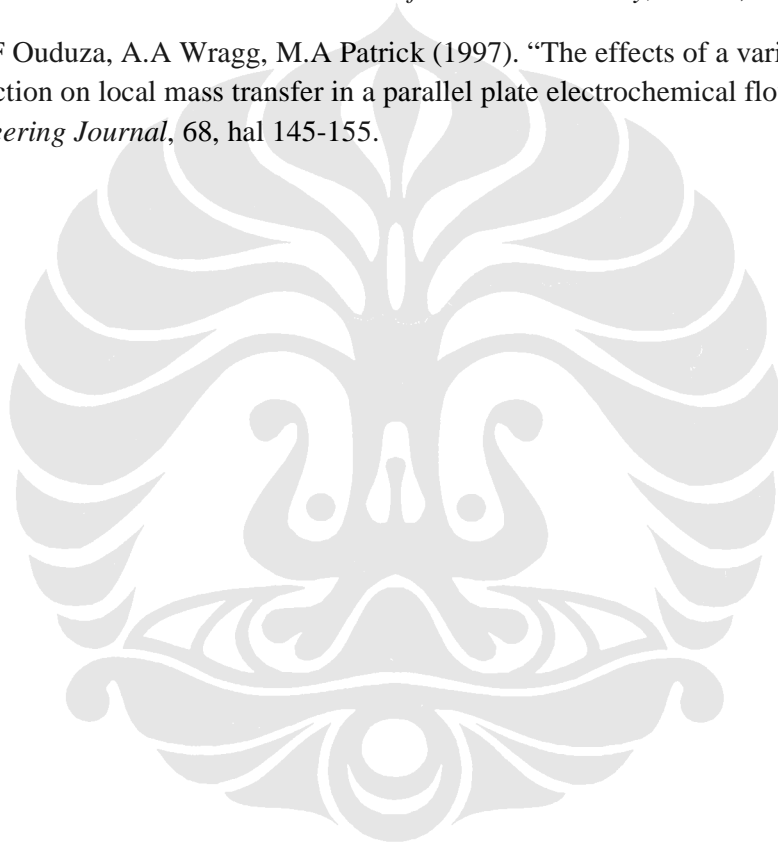


DAFTAR ACUAN

- [1] Mayer, S.T and Contolini, R.J, Electroplanarization of large and small damascene features using diffusion barriers and electropolishing, U.S Patent No. 6315883, (1999).
- [2] Chen, L., Method for electrolytically depositing copper on a semiconductor workpiece, U.S Patent No. 6290833, (2001).
- [3] Robert A. Noulty, Derek G. Leaist (1987). "Diffusion in aqueous copper sulfate and copper sulfate-sulfuric acid solutions" *Journal of solution chemistry*, vol 16, no 10, hal 813-825.
- [4] C.F Ouduza, A.A Wragg, M.A Patrick (1997). "The effects of a variety of wall obstruction on local mass transfer in a parallel plate electrochemical flow cell". *Chemical Engineering Journal*, 68, hal 145-155.



DAFTAR PUSTAKA

- Armaly, B.F., Durst, F., Pereira, J.C.F and Schonung, B., *Journal of Fluid Mechanics*, 127 (1983), pp. 473-496
- Chouikhi, S.M., Patrick, M.A., Wragg, A.A., *Journal of Applied Electrochemistry*, 17, (1987), pp 1118-1128
- Harinaldi, Laporan Penelitian Hibah PHK A3-DTM FTUI, 2007.
- Harinaldi, Proposal RUUI Program Utama, 2008.
- Incropera, Frank P., De Witt, David P., *Fundamentals of Heat and Mass Transfer*. (Singapore, Wiley and Sons, 2002)
- Keenan, Charles W. (1993). Ilmu Kimia untuk Universitas jilid 2. Jakarta: Penerbit Erlangga.
- Munson, B.R., Young D.F., Okiishi, T.H., *Mekanika Fluida*, edisi keempat, jilid 2.
- Noulty, R.A., Leaist, D.G., *Journal of Solution Chemistry*, Vol. 16, No. 10, (1987).
- Oduoza, C.F., Wragg, A.A, Patrick, M.A., *Chemical Engineering Journal*, 68 (1997) pp. 145-155.
- Runchall, A.K., *International Journal of Heat and Mass Transfer*, 14, (1971), pp. 781-792.
- Tagg, D.J., Patrick, M.A. and Wragg, A.A. *Trans. I.Chem .Eng.*, 57 (1979), pp. 176-181.
- Yang, J., Renken, A., *Chemical Engineering and Processing*, 37 (1998) pp. 537-544.
- www.ajdesigner.com/sherwood-number-equations-formula-calculator
- www.chem-is-try.org
- www.wikipedia.org